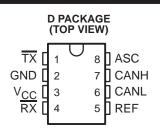
- SN75LBC031 Meets Standard ISO/DIS 11898 (up to 500 k Baud)
- Driver Output Capability at 50 mA
- Wide Positive and Negative Input/output Bus Voltage Range
- Bus Outputs Short-Circuit-Protected to Battery Voltage and Ground
- Thermal Shutdown
- Available in Q-Temp Automotive
 - HighRel Automotive Applications
 - Configuration Control/Print Support
 - Qualification to Automotive Standards

description

The SN75LBC031 is a CAN transceiver used as an interface between a CAN controller and the physical bus for high speed applications of up to 500 kBaud. The device provides transmit capability to the differential bus and differential receive capability to the controller. The transmitter outputs (CANH and CANL), feature internal transition regulation to provide controlled symmetry resulting in low EMI emissions. Both



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TERMINAL FUNCTIONS

TERMINAL	DESCRIPTION				
TX	Transmitter input				
GND	Ground				
V _{CC}	Supply voltage				
RX	Receiver output				
REF	Reference output				
CANL	Low side bus output driver				
CANH	High side bus output driver				
ASC	Adjustable slope control				

FUNCTION TABLE									
TX	CANH	CANL	BUS STATE	RX					
L	Н	L	Dominant	L					
High or floating	Floating	Floating	Recessive	Н					
L = low, H = high									

transmitter outputs are fully protected against battery short circuits and electrical transients that can occur on the bus lines. In the event of excessive device power dissipation the output drivers are disabled by the thermal shutdown circuitry at a junction temperature of approximately 160°C. The inclusion of an internal pullup resistor on the transmitter input ensures a defined output during power up and protocol controller reset. For normal operation at 500 kBaud the ASC terminal is open or tied to GND. For slower speed operation at 125 kBaud the bus output transition times can be increased to reduce EMI by connecting the ASC terminal to V_{CC}. The receiver includes an integrated filter that suppresses the signal into pulses less than 30 ns wide.

The SN75LBC031 is characterized for operation from –40°C to 85°C. The SN65LBC031 is characterized for operation from –40°C to 125°C. The SN65LBC031Q is characterized for operation over the automotive temperature range of –40°C to 125°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

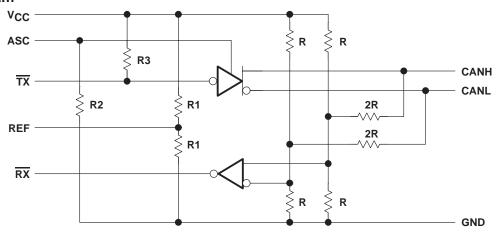
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logic diagram





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Logic supply voltage, V _{CC} (see Note 1)	
Bus terminal voltage	
Input current at \overline{TX} and ASC terminal, I ₁	±10 mA
Input voltage at \overline{TX} and ASC terminal, V_1	$\dots 2 \times V_{CC}$
Operating free-air temperature range, T _A : SN65LBC031, SN65LBC031Q	40°C to125°C
SN75LBC031	−40°C to 85°C
Operating juncation range, T _J	$\dots -40^{\circ}C$ to $150^{\circ}C$
Continuous total power dissipation at (or below) 25°C free-air temperature See Dis	sipation Rating Table
Storage temperature range, T _{stg}	−65°C to 150°C
Case temperature for 10 sec T _C , D package	260°C

 [†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
 NOTE 1: All voltage values, except differential bus voltage, are measured with respect to GND.

> **DISSIPATION RATING TABLE** $T_A \le 25^{\circ}C$ **OPERATING FACTOR** T_C = 125°C PACKAGE **POWER RATING** POWER RATING ABOVE T_C = 25°C D 725 mW 5.8 mW/°C 145 mW **DISSIPATION DERATING CURVE** VS **FREE-AIR TEMPERATURE** 1200 T_C = 25°C P_D – Maximum Continuous Dissipation – mW 1000 P = 8.8 mW/°C 800 600 D = 5.8 mW/°C 400 200 0 25 35 45 55 65 75 85 95 105 115 125 T_A – Free-Air Temperature – °C Figure 1

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recommended operating conditions

		MIN	NOM	MAX	UNIT	
Logic supply voltage, VCC	bly voltage, V _{CC} 4.5 5 5.5					
Voltage at any bus terminal (separate	-2		7	V		
High-level input voltage, VIH	TX	2		VCC	V	
Low-level input voltage, V_{IL}	TX	0		0.8	V	
High lovel output ourrest love	Transmitter			-50	mA	
	Receiver			-400	μΑ	
	Transmitter			50		
High-level output current, IOH Receiver Low-level output current, IOL Receiver	Receiver			1	mA	
Operating free-air temperature, T _A	SN75LBC031			85	°C	
	SN65LBC031, SN65LBC031Q	-40		125	Ĵ	

NOTES: 2. All voltage values, except differential bus voltage, are measured with respect to the ground terminal.

3. For bus voltages from -5 V to -2 V and 7 V to 20 V the receiver output is stable.

DATA SHEET PARAMETER	DEFINITION							
VO(CANHR)	CANH bus output voltage (recessive state)							
VO(CANLR)	CANL bus output voltage (recessive state)							
VO(CANHD)	CANH bus output voltage (dominant state)							
VO(CANLD)	CANL bus output voltage (dominant state)							
VO(DIFFR)	Bus differential output voltage (recessive state)							
V _O (DIFFD)	Bus differential output voltage (dominant state)							
V _{I(ASC)}	Adjustable slope control input voltage							

SYMBOL DEFINITION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
VO(REF)	Reference source output voltage	$I_{REF} = \pm 20 \ \mu A$	0.45 V _{CC}		0.55V _{CC}	V
R _{O(REF)}	Reference source output resistance		5		10	kΩ
ICC(REC)	Logic supply current, recessive state	See Figure 2, S1 closed		12	20	mA
ICC(DOM)	Logic supply current, dominant state			55	80	ША



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transmitter electrical characteristics over recommended ranges of supply and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
VO(CANHR) VO(CANLR)	Output voltage (recessive state)	See Figure 2, S1 open	2	0.5V _{CC}	3	V
VO(DIFFR)	Differential output voltage (recessive state)		-500	0	50	mV
VO(CANHD)	Output voltage (dominant state)		2.75	3.5	4.5	
VO(CANLD)	Output voltage (dominant state)	See Figure 2, S1 closed	0.5	1.5	2.25	V
VO(DIFFD)	Differential output voltage (dominant state)		1.5	2	3	
lu vezo	High-level input current (TX)	V _{IH} = 2.4 V		-100	-185	μA
lih(tx)		$V_{IH} = V_{CC}$			±2	μΑ
	High-level input current (ASC)	V _{IH} = 2.4 V		100	165	μA
^I IH(ASC)	nigh-level input current (ASC)	$V_{IH} = V_{CC}$		200	340	μΑ
I _{IL(TX)}	Low-level input current (\overline{TX})	V _{IL} = 0.4 V		-180	-400	μΑ
IIL(ASC)	Low-level input current (ASC)	V _{IL} = 0.4 V		15	25	μA
C _{I(TX)}	TX input capacitance			8		pF
I _{O(ssH)}	CANH short circuit output current	$V_{O(CANH)} = -2 V \text{ to } 20 V$		-95	-200	mA
I _{O(ssL)}	CANL short circuit output current	$V_{O(CANL)} = 20 V \text{ to } -2 V$		140	250	mA

NOTE 2: All voltage values, except differential bus voltage, are measured with respect to the ground terminal.

transceiver dynamic characteristics over recommended operating free-air temperature range and V_{CC} = 5 V

	PARAMETER	TEST	CONDITIONS	MIN	TYP	MAX	UNIT
4		See Figures 2 and 3, S1 closed,	VI(ASC) = 0 V or open circuit, S2 open			280	ns
^t (loop)	Loop time	See Figures 2 and 3, S1 closed,	VI(ASC) = V _{CC} , S2 closed			400	ns
SR _(RD)	Differential-output slew rate	See Figures 2 and 4, S1 closed,	VI(ASC) = 0 or open circuit, S2 open		35		V/µs
	(recessive to dominant)	See Figures 2 and 4, S1 closed,	VI(ASC) = V _{CC} , S2 closed		10		V/µs
	Differential-output slew rate	See Figures 2 and 4, S1 closed,	VI(ASC) = 0 or open circuit, S2 open		10		V/µs
SR _(DR)	(dominant to recessive)	See Figures 2 and 4, S1 closed,	VI(ASC) = VCC, S2 closed		10		V/µs
^t d(RD)	Differential output delay time		S1 alagad		55		ns
^t d(DR)	Differential-output delay time	See Figure 2,	S1 closed		160		ns
^t pd(RECRD)	Receiver propagation delay	See Figures 2 and 5			90		ns
^t pd(RECDR)	time	See rigules 2 and 5		55		ns	

NOTE 4: Receiver input pulse width should be >50 ns. Input pulses of <30 ns are suppressed.

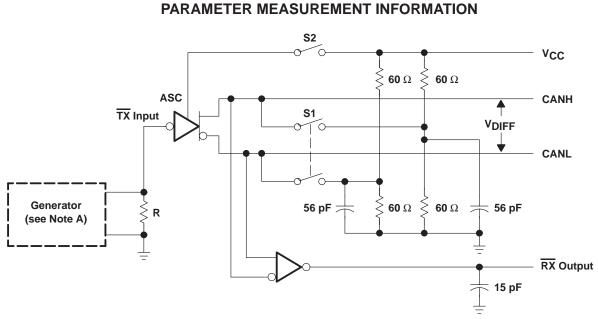


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receiver electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
VIT(REC)	Differential input threshold voltage for recessive state	$V_{IC} = -2 V \text{ to } 7 V$			500	mV
VIT(DOM)	Differential input threshold voltage for dominant state	V C = -2 V to 7 V	900			ΠV
V _{hys}	Recessive-dominant input hysteresis		100	180		mV
V _{OH(RX)}	High-level output voltage	VO(DIFF) = 500 mV, I _{OH} = -400 μA	V _{CC} -0.5 V		VCC	V
V _{OL(RX)}	Low-level output voltage	V _{O(DIFF)} = 900 mV, I _{OL} = 1 mA	0		0.5	V
rI(REC)	CANH and CANL input resistance in recessive state	dc, no load	5		50	kΩ
^r l(DIFF)	Differential CANH and CANL input resistance in recessive state	dc, no load	10		100	kΩ
Ci	CANH and CANL input capacitance			20		pF
C _{i(DHL)}	Differential CANH and CANL input capacitance			10		рF

NOTE 2: All voltage values, except differential bus voltage, are measured with respect to the ground terminal.



NOTE A: The input pulse is supplied to \overline{TX} by a generator having a t_r and t_f = 5 ns.

Figure 2. Test Circuit



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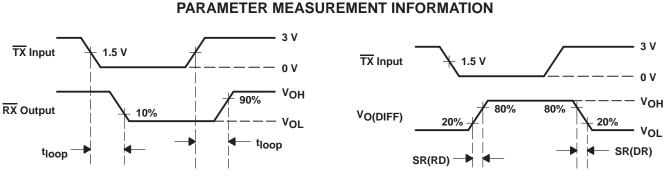
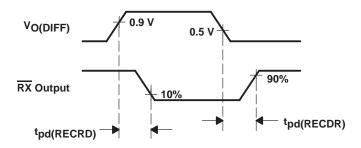


Figure 3. Loop Time

Figure 4. Slew Rate

NOTE A: The input pulse is supplied to \overline{TX} by a generator having a t_f and t_f = 5 ns.



NOTE A: The input pulse is supplied as V_{DIFF} using CANH and CANL respectively by a generator having a t_r and $t_f = 5$ ns.

Figure 5. Receiver Delay Times

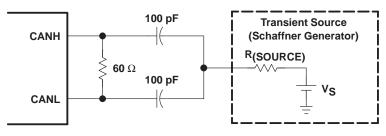


Figure 6. Transient Stress Capability Test Circuit



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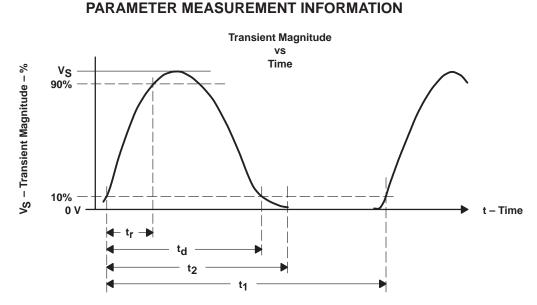


Figure 7. Transient Stress Capability Waveform

TEST PULSE	TRANSIENT MAGNITUDE VS	SOURCE IMPEDANCE RSOURCE	PULSE WIDTH ^t d (see Note 5)	PULSE RISE TIME, t _r (see Note 6)	PULSE TIME, ^t 2 (see Figure 7)	REPETITION PERIOD, t ₁ (see Figure 7)	NUMBER OF PULSES
1	–100 V	10 Ω	2 ms	1 μs	200 ms	5 s	5000
2	100 V	10 Ω	50 μs	1 μs	200 ms	5 s	5000
3a	–150 V	50 Ω	0.1 μs	5 ns	100 μs	100 μs	See Note 7
3b	100 V	50 Ω	0.1 μs	5 ns	100 μs	100 μs	See Note 7
5	60 V	1 Ω	400 ms	5 ms	—	_	1

NOTES: 5. Measured from 10% on rising edge to 10% on falling edge

6. Measured from 10% to 90% of pulse

7. Pulse package for a period of 3600 s, 10 ms pulse time, 90 ms stop time



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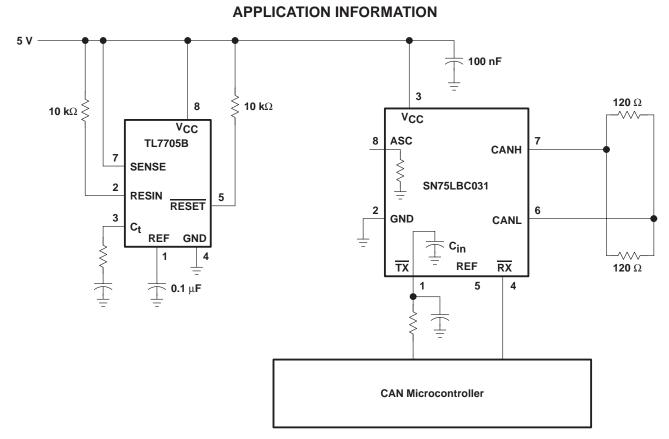


Figure 8. Typical SN75LBC031 Application



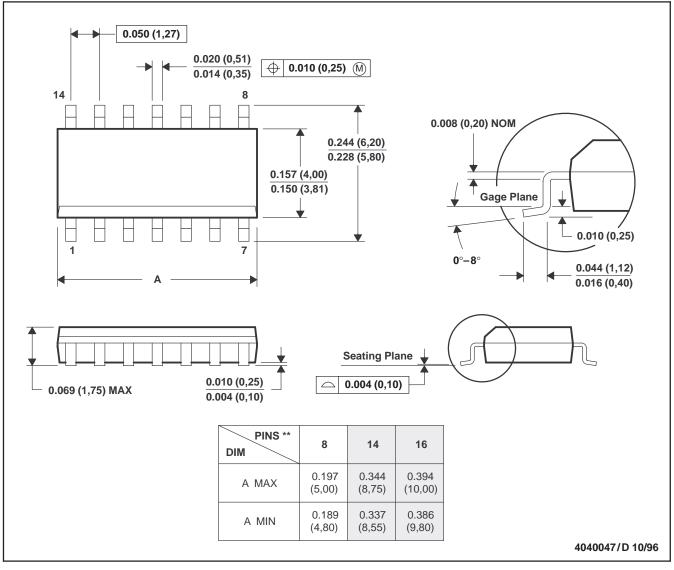
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MECHANICAL DATA

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PIN SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012





11-Apr-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing		Qty	(2)		(3)		(4)	
SN65LBC031D	ACTIVE	SOIC	D	8	75	TBD	CU NIPDAU	Level-1-220C-UNLIM	-40 to 85	6LB031	Samples
SN65LBC031DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	6LB031	Samples
SN65LBC031DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM		6LB031	Samples
SN65LBC031P	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI	-40 to 85		
SN75LBC031D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	7LB031	Samples
SN75LBC031DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	7LB031	Samples
SN75LBC031P	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI	0 to 70		

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.



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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal	
-----------------------------	--

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75LBC031DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75LBC031DR	SOIC	D	8	2500	367.0	367.0	35.0

P(R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



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